



Product/Process Change Notice - PCN 15_0024 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title: Conversion of 8x8mm and 9x9mm LFCSP Package Outlines from Punch to Sawn and Transfer of Assembly Site to Amkor Philippines

Publication Date: 01-Apr-2015

Effectivity Date: 30-Jun-2015 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Initial Release

Description Of Change

ADI has qualified and will be utilizing Assembly subcontractor Amkor in the Philippines for 8x8mm and 9x9mm LFCSP products. ADI has also qualified Amkor's standard bill of materials in a sawn singulated leadframe. There will be a change in BOM for die attach epoxy from Ablestik 8290 to Ablestik 3230. Pin1 indicator will be laser marked as part of the change. See attached for changes and package outline differences.

Reason For Change

ADI is transferring to Amkor Philippines due to the closure of Amkor Korea in October 2015.

Sawn LFCSP is ADI's technology direction for LFCSP. The use of ADI qualified Amkor-Philippines as an assembly site will ensure continued source of product supply. ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from qualified ADI manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability

The devices function and reliability as specified by the product datasheet will be unaffected by these changes. The Lead Foot Print Dimension will remain the same for both punch and sawn LFCSP packages

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Results Summary.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_15_0024_Rev_-_Qual Result Summary.pdf

Attachment 2: Type: Detailed Change Description

ADI_PCN_15_0024_Rev_-_BOM.xlsx

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Added Parts On This Revision - Product Family / Model Number (47)

AD7294 / AD7294BCPZ	AD7294 / AD7294BCPZRL	AD9861 / AD9861BCPZ-50	AD9861 / AD9861BCPZ-80	AD9861 / AD9861BCPZRL-50
AD9861 / AD9861BCPZRL-80	AD9863 / AD9863BCPZ-50	AD9863 / AD9863BCPZRL-50	ADUC816 / ADUC816BCPZ	ADUC816 / ADUC816BCPZ-REEL
ADUC824 / ADUC824BCPZ	ADUC831 / ADUC831BCPZ	ADUC831 / ADUC831BCPZ-REEL	ADUC832 / ADUC832BCPZ	ADUC832 / ADUC832BCPZ-REEL
ADUC834 / ADUC834BCPZ	ADUC834 / ADUC834BCPZ-REEL	ADUC836 / ADUC836BCPZ	ADUC836 / ADUC836BCPZ-REEL	ADUC841 / ADUC841BCPZ62-3
ADUC841 / ADUC841BCPZ62-5	ADUC841 / ADUC841BCPZ8-3	ADUC841 / ADUC841BCPZ8-5	ADUC842 / ADUC842BCPZ32-3	ADUC842 / ADUC842BCPZ32-5
ADUC842 / ADUC842BCPZ62-3	ADUC842 / ADUC842BCPZ62-5	ADUC842 / ADUC842BCPZ8-3	ADUC842 / ADUC842BCPZ8-5	ADUC843 / ADUC843BCP32Z-5
ADUC843 / ADUC843BCP62Z-5	ADUC843 / ADUC843BCPZ32-3	ADUC843 / ADUC843BCPZ62-3	ADUC843 / ADUC843BCPZ8-3	ADUC843 / ADUC843BCPZ8-5
ADUC845 / ADUC845BCPZ62-3	ADUC845 / ADUC845BCPZ62-5	ADUC845 / ADUC845BCPZ8-3	ADUC845 / ADUC845BCPZ8-5	ADUC847 / ADUC847BCPZ62-3
ADUC847 / ADUC847BCPZ62-5	ADUC847 / ADUC847BCPZ8-3	ADUC847 / ADUC847BCPZ8-5	ADUC848 / ADUC848BCPZ62-3	ADUC848 / ADUC848BCPZ62-5
ADUC848 / ADUC848BCPZ8-3	ADUC848 / ADUC848BCPZ8-5			

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	01-Apr-2015	30-Jun-2015	Initial Release

Analog Devices, Inc.

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